



## Product Change Notification - JAON-22CDLC928 (Printer Friendly)

**Date:**

31 Jan 2018

**Product Category:**

8-bit PIC Microcontrollers; Interface- Serial Peripherals; Interface- Controller Area Network (CAN)

**Notification subject:**

CCB 3000 Final Notice: Qualification of MMT as an additional assembly site using CuPdAu bond wire in selected products of the 150K and 160K wafer technologies available in 28L SSOP package.

**Notification text:****PCN Status:**

Final notification

**PCN Type:**

Manufacturing Change

**Microchip Parts Affected:**

Please open the attachments found in the attachments field below labeled as PCN\_#\_Affected\_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

**Description of Change:**

Qualification of MMT as an additional assembly site using palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 150K and 160K wafer technologies available in 28L SSOP package.

**Pre Change:**

Assembled at MTAI using palladium coated copper (PdCu) bond wire.

**Post Change:**

Assembled at MTAI using palladium coated copper (PdCu) bond wire or assembled at MMT using palladium coated copper with gold flash (CuPdAu) bond wire.

**Pre and Post Change Summary:**

	Pre Change	Post Change	
Assembly Site	Microchip Technology Thailand (HQ) / MTAI	Microchip Technology Thailand (HQ) / MTAI	Microchip Technology Thailand Branch (MMT)
Wire material	PdCu Wire	PdCu Wire	CuPdAu Wire
Die attach material	3280	3280	3280
Molding compound material	G600	G600	G600
Lead frame material	CDA194	CDA194	CDA194

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**Impacts to Data Sheet:**

None

**Change Impact:**

None

**Reason for Change:**

To improve productivity by qualifying MMT as an additional assembly site using palladium coated copper with gold flash (CuPdAu) bond wire.

**Change Implementation Status:**

In Progress

**Estimated First Ship Date:**

February 28, 2018 (date code: 1809)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

**Time Table Summary:**

	July 2017				-- >	January 2018					February 2018			
Workweek	27	28	29	30		01	02	03	04	05	06	07	08	09
Initial PCN Issue Date	X													
Qual Report Availability										X				
Final PCN Issue Date										X				
Estimated Implementation Date														X

**Method to Identify Change:**

Traceability code

**Qualification Report:**

Please open the attachments included with this PCN labeled as PCN\_#\_Qual Report

**Revision History:**

**July 6, 2017:** Issued initial notification.

**January 31, 2018:** Issued final notification. Attached the qualification report. Provided estimated first ship date to be on February 28, 2018.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

**Attachment(s):**

[PCN\\_JAON-22CDLC928\\_Qual\\_Report.pdf](#)

[PCN\\_JAON-22CDLC928\\_Affected CPN.pdf](#)

[PCN\\_JAON-22CDLC928\\_Affected CPN.xlsx](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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